EMC-OPTIMIZED CAN TRANSCEIVER

FEATURES

- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **Improved Drop-In Replacement for TJA1040**
- **Meets or Exceeds the Requirements of ISO 11898-5**
- **GIFT/ICT Compliant**
- **ESD Protection up to ±8 kV (Human-Body Model) on Bus Pins**
- **Low-Current Standby Mode With Bus Wake-Up, <12 μA Max**
- **High Electromagnetic Immunity (EMI)**
- **Low Electromagnetic Emissions (EME)**
- **Bus-Fault Protection of –27 V to 40 V**
- **Dominant Time-Out Function**
- **Thermal Shutdown Protection**
- **Power-Up/Down Glitch-Free Bus Inputs and Outputs**
  - **High Input Impedance With Low V_{CC}**
  - **Monotonic Outputs During Power Cycling**

APPLICATIONS

- **GMW3122 Dual-Wire CAN Physical Layer**
- **SAE J2284 High-Speed CAN for Automotive Applications**
- **SAE J1939 Standard Data Bus Interface**
- **ISO 11783 Standard Data Bus Interface**
- **NMEA 2000 Standard Data Bus Interface**
- **Industrial Automation**
  - **DeviceNet™ Data Buses (Vendor ID #806)**

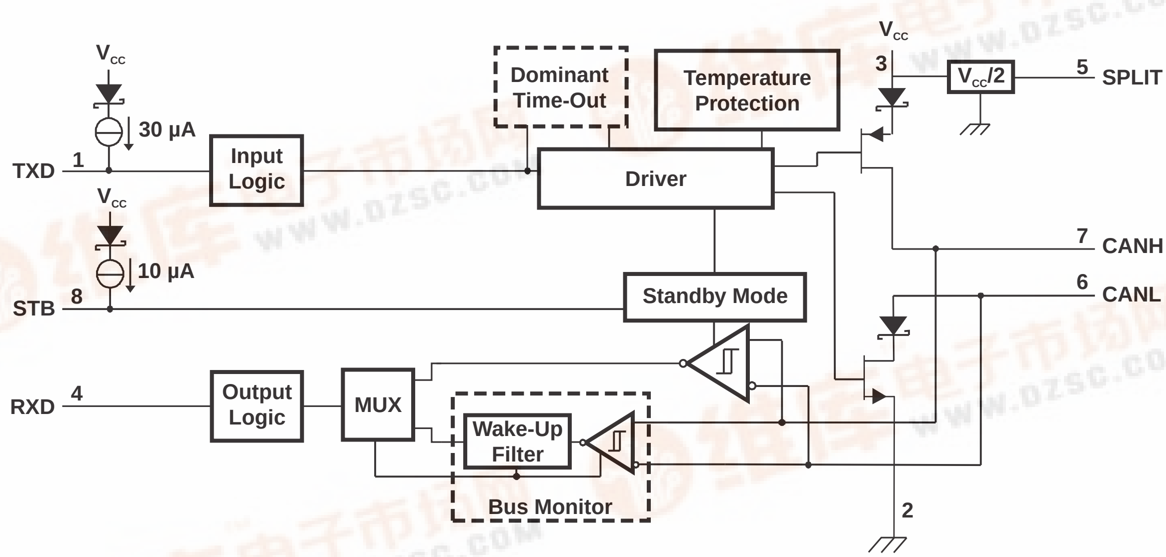
DESCRIPTION

The SN65HVD1040 meets or exceeds the specifications of the ISO 11898 standard for use in applications employing a Controller Area Network (CAN). The device is qualified for use in automotive applications.

As a CAN transceiver, this device provides differential transmit capability to the bus and differential receive capability to a CAN controller at signaling rates up to 1 megabit per second (Mbps)(1).

(1) The signaling rate of a line is the number of voltage transitions that are made per second, expressed in the units bps (bits per second).

FUNCTIONAL BLOCK DIAGRAM



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION (CONTINUED)

Designed for operation in especially harsh environments, the SN65HVD1040 features cross-wire, over-voltage, and loss of ground protection from –27 V to 40 V, over-temperature protection, a –12-V to 12-V common-mode range, and withstands voltage transients from –200 V to 200 V, according to ISO 7637.

STB (pin 8) provides two different modes of operation: high-speed mode or low-current standby mode. The high-speed mode of operation is selected by connecting STB (pin 8) to ground.

If a high logic level is applied to the STB pin of the SN65HVD1040, the device enters a low-current standby mode, while the receiver remains active in a low-power bus-monitor standby mode.

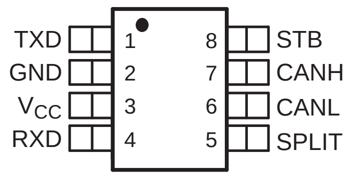
In the low-current standby mode, a dominant bit greater than 5 µs on the bus is passed by the bus-monitor circuit to the receiver output. The local protocol controller may then reactivate the device when it needs to transmit to the bus.

A dominant time-out circuit in the SN65HVD1040 prevents the driver from blocking network communication with a hardware or software failure. The time-out circuit is triggered by a falling edge on TXD (pin 1). If no rising edge is seen before the time-out constant of the circuit expires, the driver is disabled. The circuit is then reset by the next rising edge on TXD.

SPLIT (pin 5) is available as a $V_{CC}/2$ common-mode bus voltage bias for a split-termination network (see application information).

The SN65HVD1040 is characterized for operation from –40°C to 125°C.

SN65HVD1040



ORDERING INFORMATION(1)

PART NUMBER	PACKAGE(2)	MARKED AS	ORDERING NUMBER
SN65HVD1040-Q1	SOIC-8	H1040Q	SN65HVD1040QDRQ1 (reel)

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

Application Hint: CAN Nodes Using Common-Mode Chokes

The SN65HVD1040 has been EMC optimized to allow use in CAN systems without a common-mode choke. However, sometimes the CAN network and termination architecture may require their use. If a common-mode choke is used in a CAN node where bus line shorts to dc voltages may be possible, care should be taken in the choice of common-mode choke (winding type, core type, and value) along with the termination and protection scheme of the node and bus. During CAN bus shorts to dc voltages the inductance of the common-mode choke may cause inductive flyback transients. Some combinations of common-mode chokes, bus termination, and shorting voltages can take the bus voltages outside the absolute maximum ratings of the device, possibly leading to damage.

ABSOLUTE MAXIMUM RATINGS[1][2]

over operating free-air temperature range (unless otherwise noted)

		VALUE
V_{CC}	Supply voltage range	–0.3 V to 7 V
	Voltage range at bus terminals (CANH, CANL, SPLIT)	–27 V to 40 V
I_O	Receiver output current	20 mA
V_I	Voltage input range, ac transient pulse[3] (CANH, CANL)	–200 V to 200 V
V_I	Voltage input range (TXD, STB)	–0.5 V to 6 V
T_J	Junction temperature range	–40°C to 170°C
T_A	Operating free-air temperature range	–40°C to 125°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
(3) Tested in accordance with ISO 7637-1, test pulses 1, 2, 3a, 3b, 5, 6, and 7. ISO 7637-1 transient tests are ac only; if dc may be coupled in with ac transients, externally protect the bus pins within the absolute maximum voltage range at any bus terminal (–27 V to 40 V). If common-mode chokes are used in the system and the bus lines may be shorted to dc, ensure that the choke type and value in combination with the node termination and shorting voltage either does not create inductive flyback outside of voltage maximum specification or use an external transient-suppression circuit to protect the transceiver from the inductive transients.

ELECTROSTATIC DISCHARGE PROTECTION

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		VALUE
Electrostatic discharge[1]	Human-Body Model[2]	Bus terminals (CANH, CANL, SPLIT) and GND	±8 kV
		All pins	±4 kV
	Charged-Device Model[3]	All pins	±1 kV
	Machine Model		±200 V

(1) All typical values at 25°C.
(2) Tested in accordance JEDEC Standard 22, Test Method A114-A.
(3) Tested in accordance JEDEC Standard 22, Test Method C101.

RECOMMENDED OPERATING CONDITIONS

			MIN	MAX	UNIT
V_{CC}	Supply voltage		4.75	5.25	V
V_I or V_{IC}	Voltage at any bus terminal (separately or common mode)		–12	12	V
V_{IH}	High-level input voltage	TXD, STB	2	5.25	V
V_{IL}	Low-level input voltage	TXD, STB	0	0.8	V
V_{ID}	Differential input voltage		–6	6	V
I_{OH}	High-level output current	Driver	–70		mA
		Receiver	–2		
I_{OL}	Low-level output current	Driver		70	mA
		Receiver		2	
T_J	Junction temperature	See Thermal Characteristics table		150	°C

SUPPLY CURRENT

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC}	5-V supply current	Standby mode	STB at V_{CC}, $V_I = V_{CC}$		6	12	µA
		Dominant	V_I = 0 V, 60-Ω load, STB at 0 V		50	70	mA
		Recessive	$V_I = V_{CC}$, No load, STB at 0 V		6	10	

DEVICE SWITCHING CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$t_{d(LOOP1)}$	Total loop delay, driver input to receiver output, recessive to dominant	STB at 0 V, See Figure 9	90	230	ns
$t_{d(LOOP2)}$	Total loop delay, driver input to receiver output, dominant to recessive		90	230	ns

DRIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP (1)	MAX	UNIT
$V_{O(D)}$	Bus output voltage (dominant)	CANH	V_I = 0 V, STB at 0 V, R_L = 60 Ω, See Figure 1 and Figure 2	2.9	3.4	4.5	V
		CANL		0.8		1.75	
$V_{O(R)}$	Bus output voltage (recessive)		V_I = 3 V, STB at 0 V, R_L = 60 Ω, See Figure 1 and Figure 2	2	2.5	3	V
V_O	Bus output voltage (standby mode)		STB at Vcc, R_L = 60 Ω, See Figure 1 and Figure 2	–0.1		0.1	V
$V_{OD(D)}$	Differential output voltage (dominant)		V_I = 0 V, R_L = 60 Ω, STB at 0 V, See Figure 1, Figure 2, and Figure 3	1.5		3	V
			V_I = 0 V, R_L = 45 Ω, STB at 0 V, See Figure 1, Figure 2, and Figure 3	1.4		3	
$V_{OD(R)}$	Differential output voltage (recessive)		V_I = 3 V, STB at 0 V, R_L = 60 Ω, See Figure 1 and Figure 2	–0.012		0.012	V
			V_I = 3 V, STB at 0 V, No load	–0.5		0.05	
V_{SYM}	Output symmetry (dominant or recessive) ($V_{O(CANH)} + V_{O(CANL)}$)		STB at 0 V, R_L = 60 Ω, See Figure 13	0.9 V_{CC}	V_{CC}	1.1 V_{CC}	V
$V_{OC(ss)}$	Steady-state common-mode output voltage		STB at 0 V, R_L = 60 Ω, See Figure 8	2	2.5	3	V
$\Delta V_{OC(ss)}$	Change in steady-state common-mode output voltage		STB at 0 V, R_L = 60 Ω, See Figure 8		30		mV
I_{IH}	High-level input current, TXD input		V_I at V_{CC}	–2		2	μA
I_{IL}	Low-level input current, TXD input		V_I at 0 V	–50		–10	μA
$I_{O(off)}$	Power-off TXD output current		V_{CC} at 0 V, TXD at 5 V			1	μA
$I_{OS(ss)}$	Short-circuit steady-state output current		V_{CANH} = –12 V, CANL open, See Figure 11	–120	–85		mA
			V_{CANH} = 12 V, CANL open, See Figure 11		0.4	1	
			V_{CANL} = –12 V, CANH open, See Figure 11	–1	–0.6		
			V_{CANL} = 12 V, CANH open, See Figure 11		75	120	
C_O	Output capacitance		See receiver input capacitance				

(1) All typical values are at 25°C with a 5-V supply.

DRIVER SWITCHING CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high level output	STB at 0 V, See Figure 4	25	65	120	ns
t_{PHL}	Propagation delay time, high-to-low level output	STB at 0 V, See Figure 4	25	45	120	ns
t_r	Differential output signal rise time	STB at 0 V, See Figure 4		25		ns
t_f	Differential output signal fall time	STB at 0 V, See Figure 4		45		ns
t_{en}	Enable time from standby mode to dominant	See Figure 7			10	μs
$t_{(dom)}$	Dominant time out	↓V_I, See Figure 10	300	450	700	μs

RECEIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage, high-speed mode	STB at 0 V, See Table 1		800	900	mV
V_{IT-}	Negative-going input threshold voltage, high-speed mode	STB at 0 V, See Table 1	500	650		mV
V_{hys}	Hysteresis voltage ($V_{IT+} – V_{IT–}$)		100	125		mV
V_{IT}	Input threshold voltage, standby mode	STB at V_{CC}	500		1150	mV
V_{OH}	High-level output voltage	I_O = –2 mA, See Figure 6	4	4.6		V
V_{OL}	Low-level output voltage	I_O = 2 mA, See Figure 6		0.2	0.4	V
$I_{I(off)}$	Power-off bus input current	CANH = CANL = 5 V, V_{CC} at 0 V, TXD at 0 V			3	µA
$I_{O(off)}$	Power-off RXD leakage current	V_{CC} at 0 V, RXD at 5 V			20	µA
C_I	Input capacitance to ground (CANH or CANL)	TXD at 3 V, V_I = 0.4 sin (4E6πt) + 2.5 V		12		pF
C_{ID}	Differential input capacitance	TXD at 3 V, V_I = 0.4 sin (4E6πt)		2		pF
R_{ID}	Differential input resistance	TXD at 3 V, STB at 0 V	30		80	kΩ
R_{IN}	Input resistance (CANH or CANL)	TXD at 3 V, STB at 0 V	15	30	40	kΩ
$R_{I(m)}$	Input resistance matching [1 – ($R_{IN (CANH)}$ / $R_{IN (CANL)}$)] × 100%	$V_{(CANH)} = V_{(CANL)}$	–3	0	3	%

(1) All typical values are at 25°C with a 5-V supply.

RECEIVER SWITCHING CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	STB at 0 V , See Figure 6	60	90	130	ns
t_{PHL}	Propagation delay time, high-to-low-level output	STB at 0 V , See Figure 6	45	70	130	ns
t_r	Output signal rise time	STB at 0 V , See Figure 6		8		ns
t_f	Output signal fall time	STB at 0 V , See Figure 6		8		ns
t_{BUS}	Dominant time required on bus for wake-up from standby	STB at V_{CC}, See Figure 12	1.5		5	µs

STB PIN CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
I_{IH}	High-level input current	STB at V_{CC}	–10	0	µA
I_{IL}	Low-level input current	STB at 0 V	–10	0	µA

SPLIT PIN CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_O	Output voltage	–500 µA < I_O < 500 µA	0.3 V_{CC}	0.5 V_{CC}	0.7 V_{CC}	V
$I_{O(stb)}$	Leakage current, standby mode	STB at 2 V, –12 V ≤ V_O ≤ 12 V	–5		5	µA

THERMAL CHARACTERISTICS

over recommended operating conditions including operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
θ_{JA}	Junction-to-air thermal resistance	Low-K thermal resistance (1)		211		°C/W
		High-K thermal resistance		131		
θ_{JB}	Junction-to-board thermal resistance			53		°C/W
θ_{JC}	Junction-to-case thermal resistance			79		°C/W
P_D	Average power dissipation	V_{CC} = 5 V, T_J = 27°C, R_L = 60 Ω, STB at 0 V, Input to TXD at 500 kHz, 50% duty cycle square wave, C_L at RXD = 15 pF		112		mW
		V_{CC} = 5.5 V, T_J = 130°C, R_L = 45 Ω, STB at 0 V, Input to TXD at 500 kHz, 50% duty cycle square wave, C_L at RXD = 15 pF			170	
	Thermal shutdown temperature			185		°C

(1) Tested in accordance with the low-K or high-K thermal metric definitions of EIA/JESD51-3 for leaded surface-mount packages.

FUNCTION TABLES

DRIVER (1)

INPUTS		OUTPUTS		BUS STATE
TXD	STB	CANH	CANL	
L	L	H	L	Dominant
H	L	Z	Z	Recessive
Open	L	Z	Z	Recessive
X	H or Open	Y	Y	Recessive

(1) H = high level, L = low level, X = irrelevant, ? = indeterminate, Y = weak pulldown do GND, Z = high impedance

RECEIVER (1)

DIFFERENTIAL INPUTS V_{ID} = V(CANH) – V(CANL)	STB	OUTPUT RXD	BUS STATE
$V_{ID} \geq 0.9$ V	L	L	Dominant
$V_{ID} \geq 1.15$ V	H or Open	L	Dominant
0.5 V < V_{ID} < 0.9 V	X	?	?
$V_{ID} \leq 0.5$ V	X	H	Recessive
Open	X	H	Recessive

(1) H = high level, L = low level, X = irrelevant, ? = indeterminate, Z = high impedance

PARAMETER MEASUREMENT INFORMATION

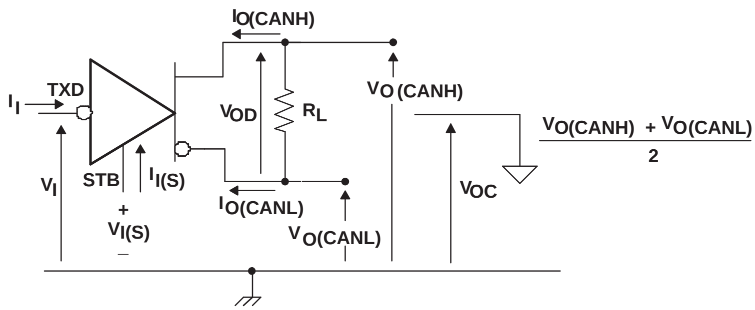


Figure 1. Driver Voltage, Current, and Test Definition

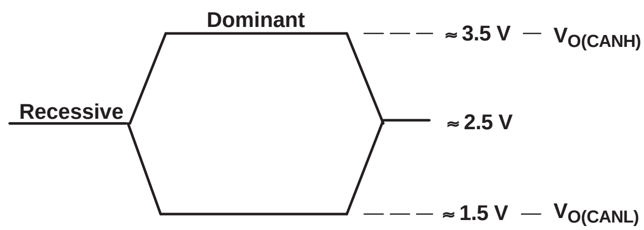


Figure 2. Bus Logic-State Voltage Definitions

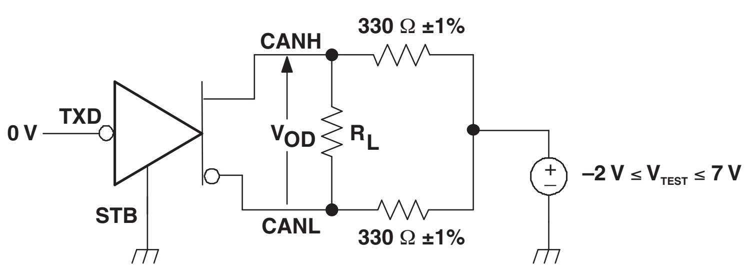


Figure 3. Driver V_{OD} Test Circuit

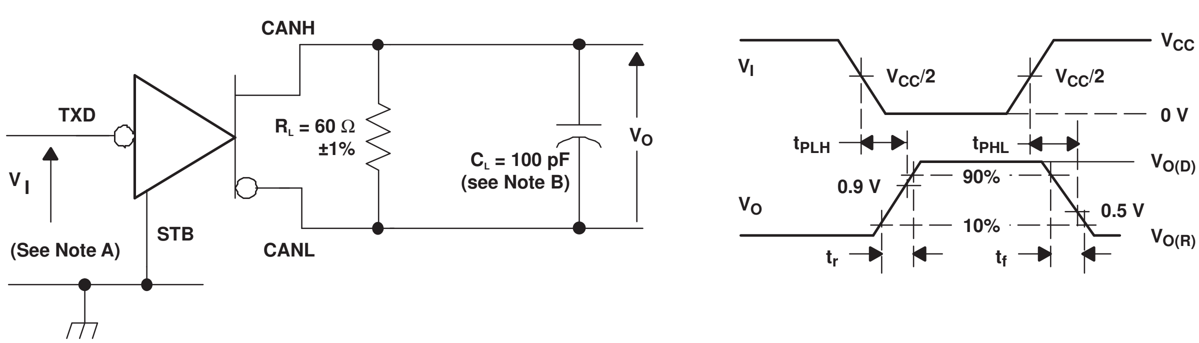


Figure 4. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)

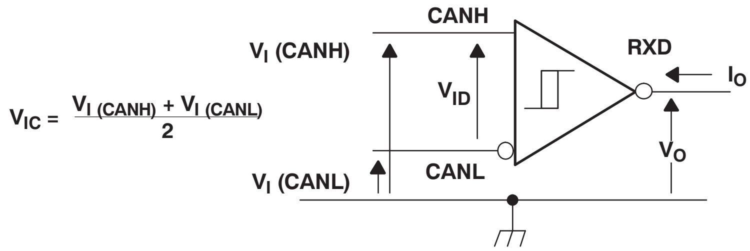
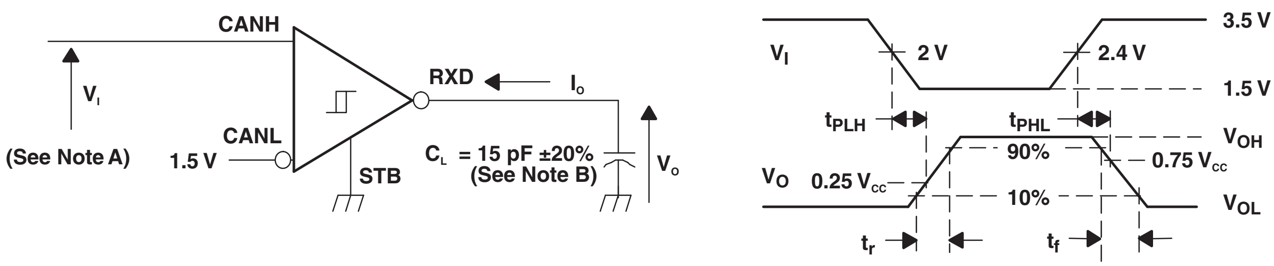


Figure 5. Receiver Voltage and Current Definitions



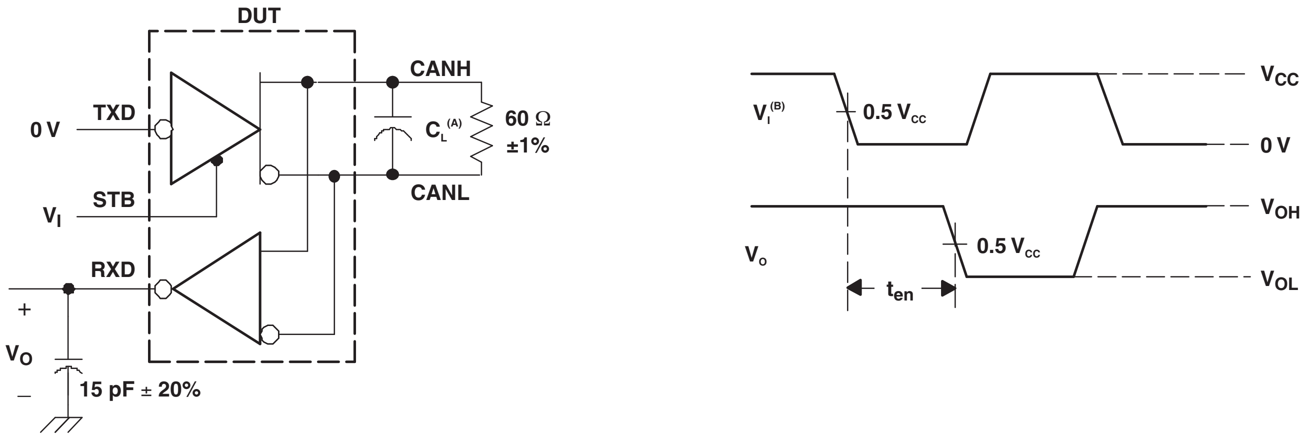
A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 125 kHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

B. C_L includes instrumentation and fixture capacitance within ±20%.

Figure 6. Receiver Test Circuit and Voltage Waveforms

Table 1. Differential Input Voltage Threshold Test

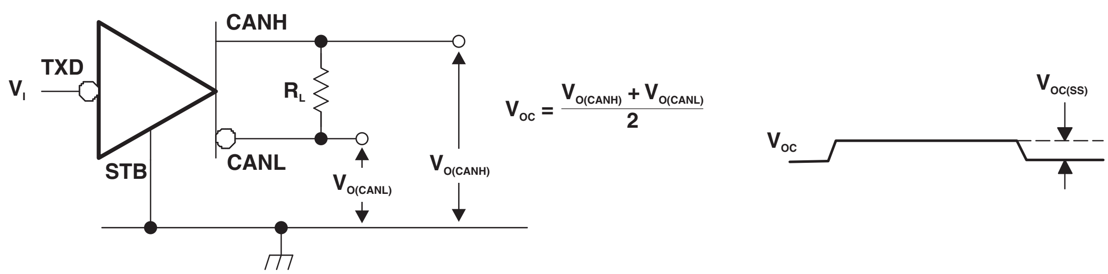
INPUT			OUTPUT	
V_{CANH}	V_{CANL}	$\lvert V_{ID} \rvert$	R	
–11.1 V	–12 V	900 mV	L	V_{OL}
12 V	11.1 V	900 mV	L	
–6 V	–12 V	6 V	L	
12 V	6 V	6 V	L	
–11.5 V	–12 V	500 mV	H	V_{OH}
12 V	11.5 V	500 mV	H	
–12 V	–6 V	6 V	H	
6 V	12 V	6 V	H	
Open	Open	X	H	



A. C_L = 100 pF and includes instrumentation and fixture capacitance within ±20%.

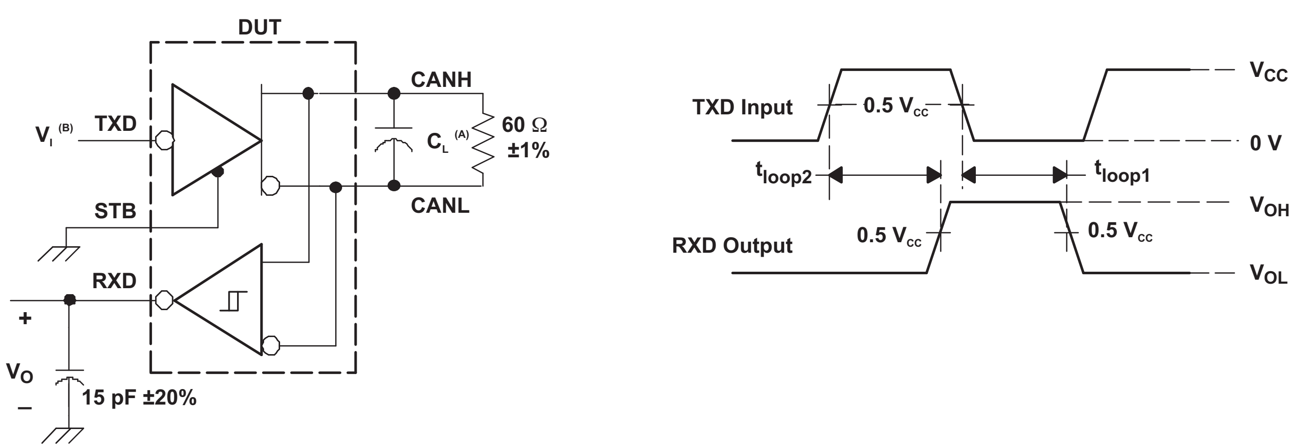
B. All V_I input pulses are supplied by a generator having the following characteristics: t_r or t_f ≤ 6 ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

Figure 7. t_{en} Test Circuit and Waveforms



NOTE: All V_I input pulses are from 0 V to V_{CC} and supplied by a generator having the following characteristics: t_r or t_f ≤ 6 ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

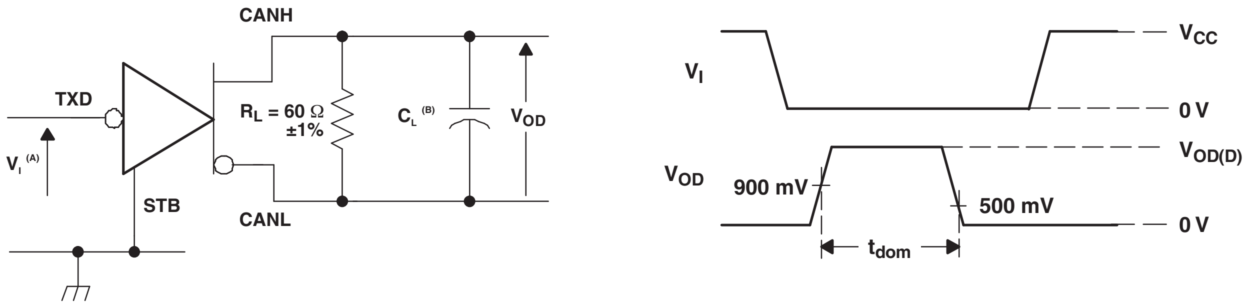
Figure 8. Common-Mode Output Voltage Test and Waveforms



A. C_L = 100 pF and includes instrumentation and fixture capacitance within ±20%.

B. All V_I input pulses are from 0 V to V_{CC} and supplied by a generator having the following characteristics: t_r or t_f ≤ 6 ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

Figure 9. $t_{(LOOP)}$ Test Circuit and Waveforms



A. All V_I input pulses are from 0 V to V_{CC} and supplied by a generator having the following characteristics: t_r or t_f ≤ 6 ns, pulse repetition rate (PRR) = 500 Hz, 50% duty cycle.

B. C_L = 100 pF includes instrumentation and fixture capacitance within ±20%.

Figure 10. Dominant Time-Out Test Circuit and Waveforms

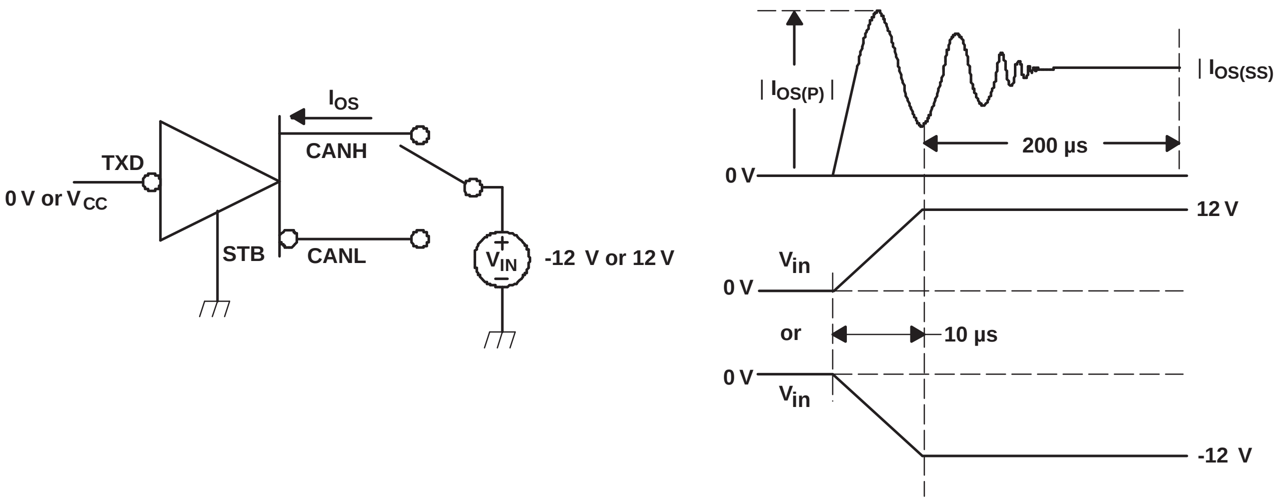
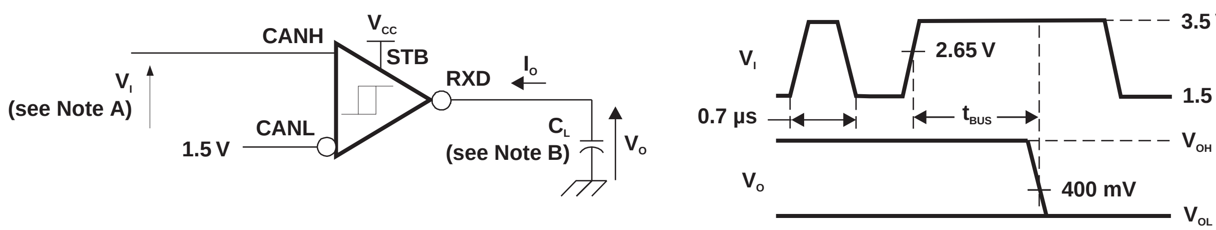


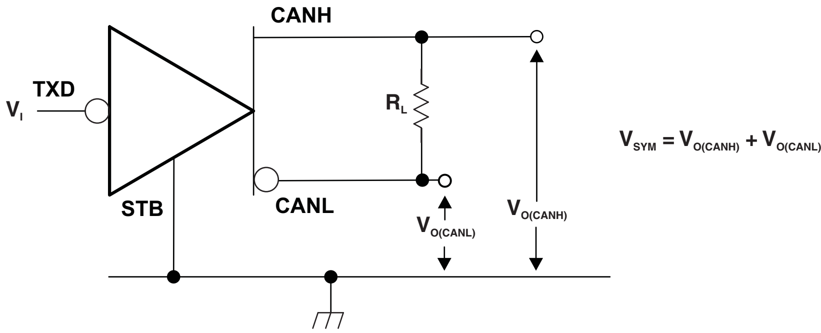
Figure 11. Driver Short-Circuit Current Test and Waveforms



A. For V_I bit width ≤ 0.7 µs, V_O = V_{OH}. For V_I bit width ≥ 5 µs, V_O = V_{OL}. V_I input pulses are supplied from a generator with the following characteristics: t_r/t_f < 6 ns.

B. C_L = 15 pF and includes instrumentation and fixture capacitance within ±20%.

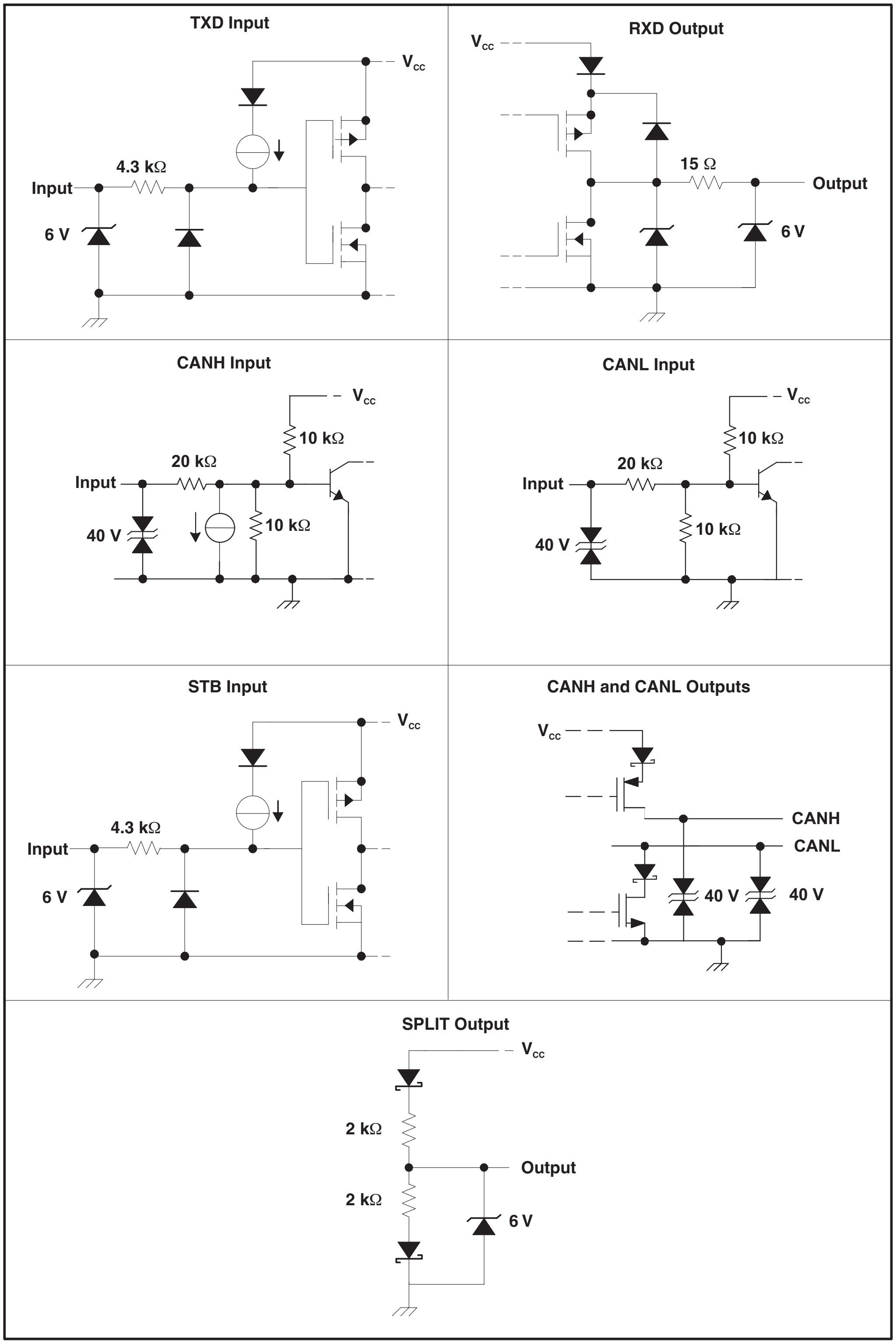
Figure 12. t_{BUS} Test Circuit and Waveforms



A. All V_I input pulses are from 0 V to V_{CC} and supplied by a generator having the following characteristics: $t_r/t_f \leq 6$ ns, pulse repetition rate (PRR) = 250 kHz, 50% duty cycle.

Figure 13. Driver Output Symmetry Test Circuit

Equivalent Input and Output Schematic Diagrams



APPLICATION INFORMATION

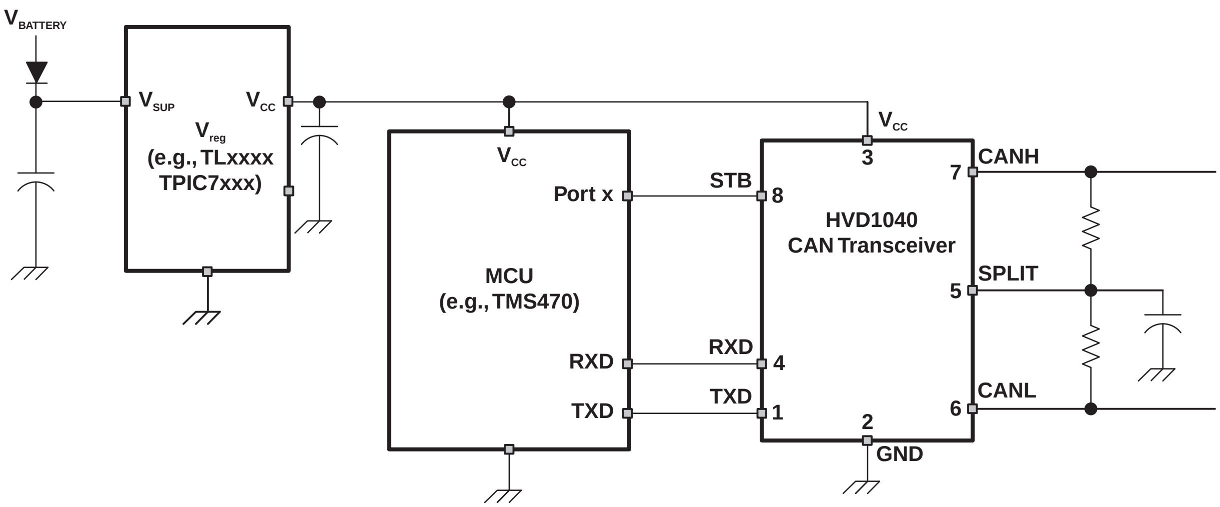


Figure 14. Typical Application Using Split Termination for Stabilization

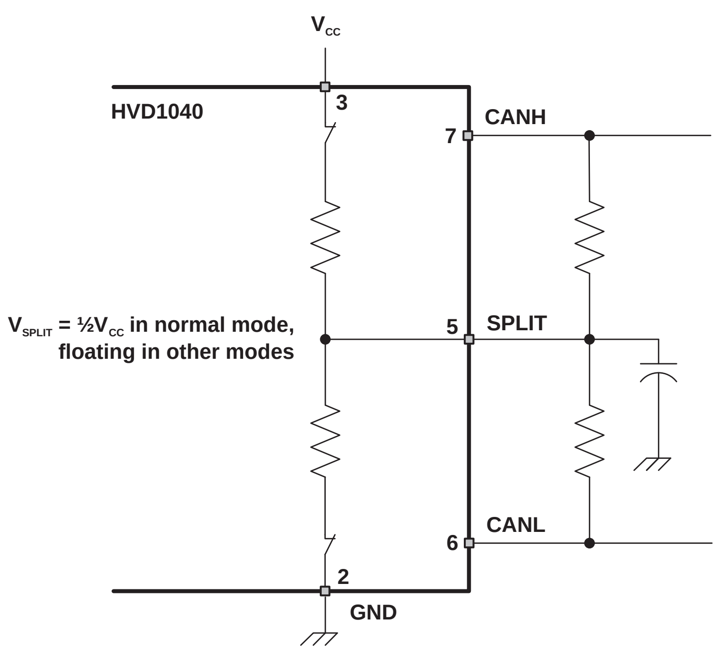


Figure 15. Split Pin Stabilization Circuitry and Application

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN65HVD1040QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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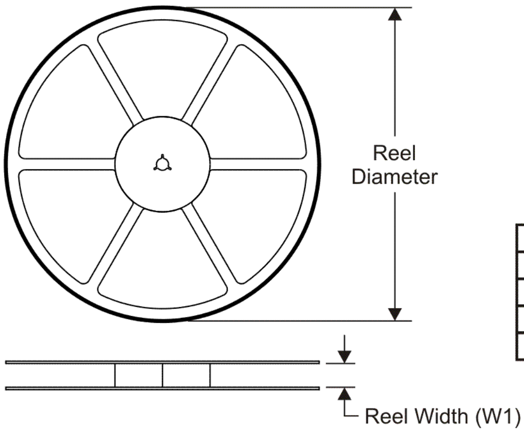
OTHER QUALIFIED VERSIONS OF SN65HVD1040-Q1 :
- Catalog: SN65HVD1040

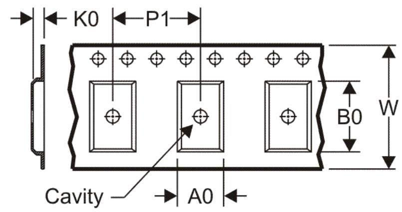
NOTE: Qualified Version Definitions:
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

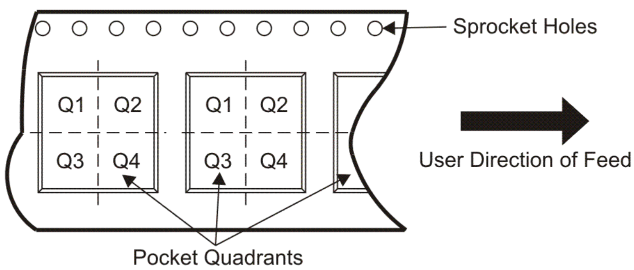


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

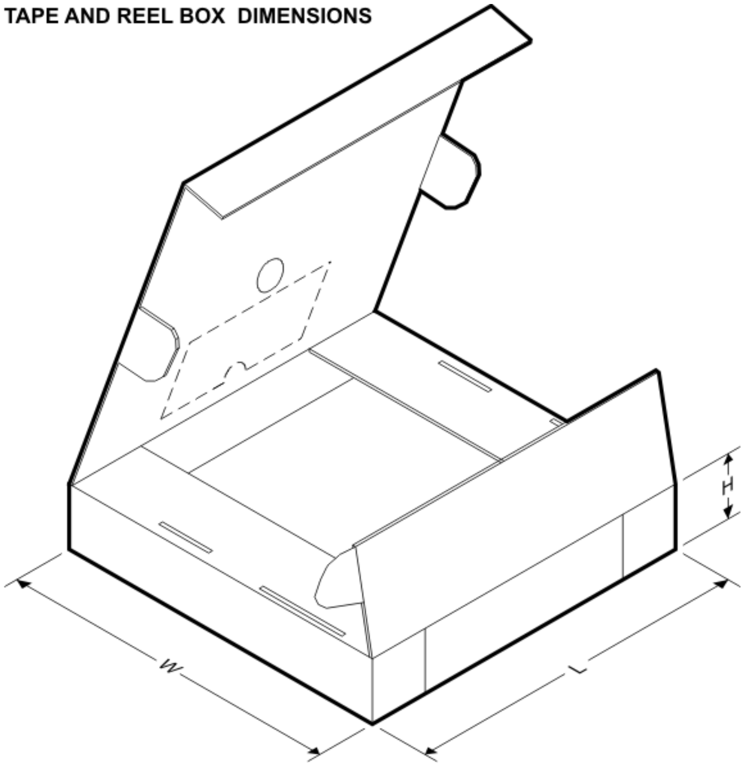
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65HVD1040QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

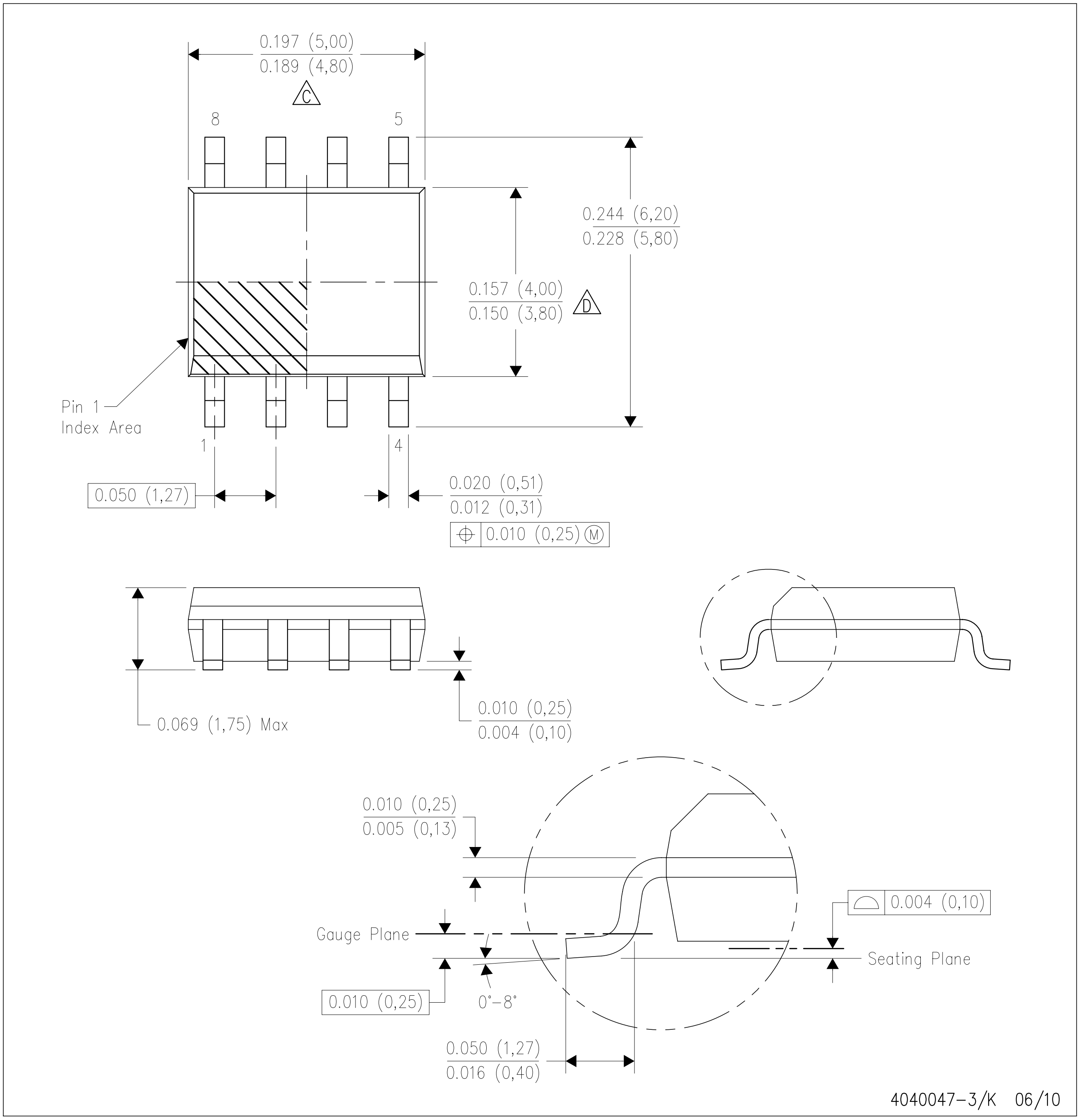


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65HVD1040QDRQ1	SOIC	D	8	2500	346.0	346.0	29.0

查询"SN65HVD1040-Q1"供应商

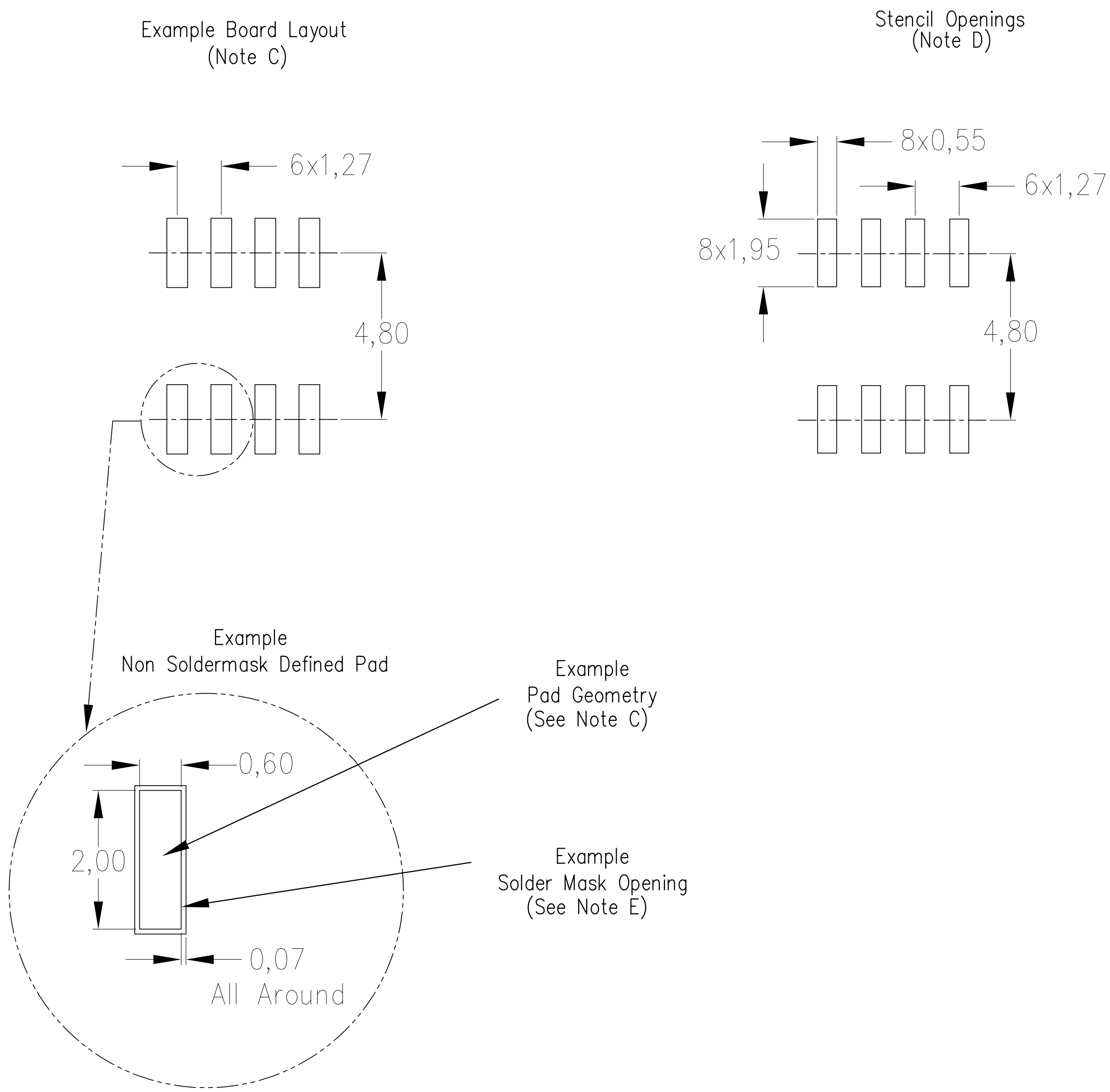
D (R-PDSO-G8) PLASTIC SMALL-OUTLINE PACKAGE



NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.

查询"SN65HVD1040-Q1"供应商

D (R-PDSO-G8) PLASTIC SMALL OUTLINE



4211283-2/B 09/10

NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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